

DECLARED PROCESS LIST		ORIGINATOR: UK ATC	
SPACECRAFT / PROJECT:	Herschel	Doc. Number	SPIRE-ATC-PRJ-708
SYSTEM / EXPERIMENT:	SPIRE	Sheet No	Page 1 of 2
SUB-SYSTEM:	BSM	Issue:	0.1
		Date:	24.Jun. 01

Process ID	Process	Specification (Incl. Issue)	Description / Identification	Use and Location	User Code	Associated DML Items	Criticality of Process	Approval / Status
1.	Adhesive bonding		Bonding of sensors into mounts	Jiggle frame & structure		Eccobond, G-10,	medium	
2.	Adhesive bonding		Bonding of flex-pivots into sleeves	Chop and Jiggle stage		inconel, Eccobond, aluminium 6082	high	
3.	Adhesive bonding		Bonding of sleeves into housings	Chop and Jiggle stage		Eccobond, aluminium 6082	high	
4.	Adhesive bonding		Harness tie-down (TBD if required)			Eccobond, aluminium 6082	low	
5.	Adhesive bonding		fastener locking (TBD if required)			Eccobond, aluminium 6082, stainless steel	medium	
6.	Adhesive bonding		Bonding of magnets into pockets	Chop and Jiggle stage		Eccobond, aluminium 6082/6061, magnet	medium	
7.	Adhesive bonding		Bonding of sensor actuators into pockets	Chop and Jiggle stage		Eccobond, aluminium 6082/6061, soft iron	medium	
8.	Thermal stabilization		Mirror stability cycling	Chop stage		Aluminium 6061	high	
9.	Gold plating 5 um			thermal contact		Gold, copper, nickel plate		
10.	Gold plating 3 um			Emmissivity control		Gold, copper, nickel plate		
11.	Anodizing			Corrosion control				
12.	Varnish application			Insulation/corrosion control				
13.	Soldering			Connectors				
14.	Crimping			Connectors				

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